

WSR140N10

N-Ch MOSFET

#### **General Description**

The WSR140N10 is the highest performance trench N-Ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications.

The WSR140N10 meet the RoHS and Green Product requirement,100% EAS guaranteed with full function reliability approved.

#### Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

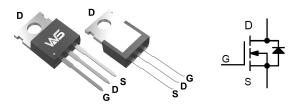
### **Product Summery**

BV <sub>DSS</sub>	R <sub>DSON</sub>	I <sub>D</sub>
100V	3.7mΩ	140A

### Applications

- Power Management in TV Converter.
- DC-DC Converter
- LED TV Back Light

### **TO-220AB** Pin Configuration



### Absolute Maximum Ratings

Symbol	Parameter	Rating	Units
V <sub>DS</sub>	Drain-Source Voltage	100	V
V <sub>GS</sub>	Gate-Source Voltage	±25	V
I <sub>D</sub> @T <sub>C</sub> =25℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	140	A
I <sub>D</sub> @T <sub>C</sub> =100℃	Continuous Drain Current, V <sub>GS</sub> @ 10V <sup>1</sup>	90	А
I <sub>DM</sub>	Pulsed Drain Current <sup>2,</sup> T <sub>C</sub> =25°C	600	А
EAS	Avalanche Energy, Single pulse	545	mJ
I <sub>AS</sub>	Avalanche Current, Single pulse	60	A
P <sub>D</sub> @T <sub>C</sub> =25℃	Total Power Dissipation <sup>4</sup>	225	W
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C
TJ	Operating Junction Temperature Range	150	°C

#### **Thermal Data**

Symbol	Parameter	Тур.	Max.	Unit	
R <sub>0JA</sub>	Thermal Resistance Junction-Ambient <sup>1</sup>		50	°C/W	
R <sub>θJC</sub>	Thermal Resistance Junction-Case <sup>1</sup>		0.55	°C/W	



**N-Ch MOSFET** 

### Electrical Characteristics (T<sub>J</sub>=25 C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	100			V	
$\triangle BV_{DSS} / \triangle T_J$	BV <sub>DSS</sub> Temperature Coefficient	Reference to $25^{\circ}$ C , I <sub>D</sub> =1mA		0.096		V/℃	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =10V , I <sub>D</sub> =80A		3.7	4.2	mΩ	
V <sub>GS(th)</sub>	Gate Threshold Voltage		2.5	3.0	4.5	V	
$ riangle V_{GS(th)}$	V <sub>GS(th)</sub> Temperature Coefficient	$-V_{GS}=V_{DS}$ , I <sub>D</sub> =250uA		-5.5		mV/℃	
	Drain-Source Leakage Current	$V_{\text{DS}}\text{=}80\text{V}$ , $V_{\text{GS}}\text{=}0\text{V}$ , $T_{\text{J}}\text{=}25^\circ\!\mathrm{C}$			1	uA	
I <sub>DSS</sub>	Drain-Source Leakage Current	$V_{DS}$ =80V , $V_{GS}$ =0V , $T_{J}$ =55 $^{\circ}\mathrm{C}$			5		
I <sub>GSS</sub>	Gate-Source Leakage Current	$V_{GS}$ = $\pm20V$ , $V_{DS}$ = $0V$			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =50A		120		S	
R <sub>g</sub>	Gate Resistance	$V_{DS}$ =0V , $V_{GS}$ =0V , f=1MHz		0.7	1.5	Ω	
Qg	Total Gate Charge (10V)			80			
Q <sub>gs</sub>	Gate-Source Charge	$V_{DS}$ =80V , $V_{GS}$ =10V , $I_{D}$ =80A		33		nC	
Q <sub>gd</sub>	Gate-Drain Charge			18			
T <sub>d(on)</sub>	Turn-On Delay Time			28			
Tr	Rise Time	$V_{DD}$ =50V , $V_{GS}$ =10V ,		55			
T <sub>d(off)</sub>	Turn-Off Delay Time	R <sub>G</sub> =5Ω, I <sub>D</sub> =80A		98		ns	
T <sub>f</sub>	Fall Time			24			
C <sub>iss</sub>	Input Capacitance			4120			
Coss	Output Capacitance	V <sub>DS</sub> =50V , V <sub>GS</sub> =0V , f=1MHz		1250		pF	
C <sub>rss</sub>	Reverse Transfer Capacitance			65			

### **Diode Characteristics**

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I <sub>S</sub>	Continuous Source Current <sup>1,6</sup>	$V_G=V_D=0V$ , Force Current			80	А
V <sub>SD</sub>	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =50A , TJ=25℃		0.8	1.3	V
t <sub>rr</sub>	Reverse Recovery Time			85		nS
Qrr	Reverse Recovery Charge	IF=50A,dI/dt=100A/µs,Tյ=25℃		200		nC

Note :

1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper,t<10sec. 2. The data tested by pulsed , pulse width  $\leq$  300us , duty cycle  $\leq$  2% 3. The EAS data shows Max. rating . The test condition is V<sub>DS</sub>=80V,V<sub>GS</sub>=10V,L=0.1mH,

5. The Min. value is 100% EAS tested guarantee.

6.The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.

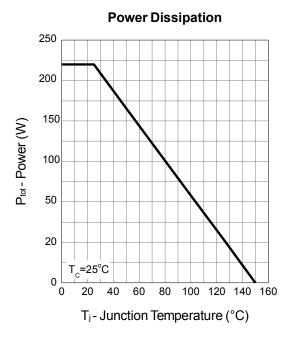
<sup>4.</sup> The power dissipation is limited by 150  $^\circ\!\mathrm{C}$  junction temperature

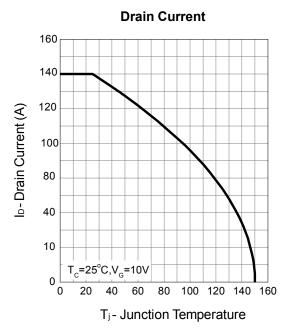


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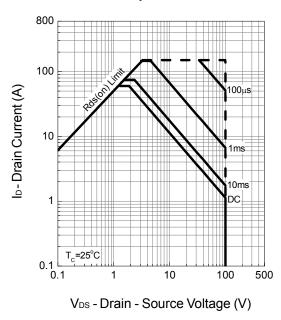
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# **Typical Operating Characteristics**

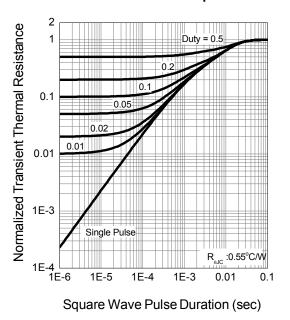




Safe Operation Area



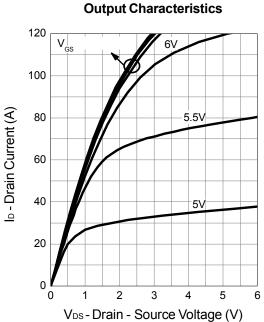
**Thermal Transient Impedance** 





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# **Typical Operating Characteristics (Cont.)**

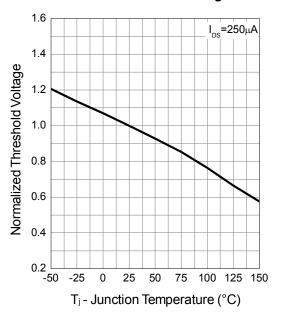


7.0 V<sub>GS</sub>=10V 6.0  $R_{DS(ON)}$  - On - Resistance (m $\Omega$ ) 5.0 4.0 3.0 2.0 0 L 0 20 40 60 80 100 ID-Drain Current (A)

**Drain-Source On Resistance** 

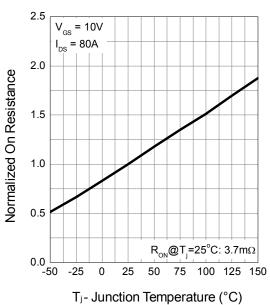
**Gate-Source On Resistance** 40 I<sub>DS</sub>=80A 35  $R_{DS(ON)}$  - On - Resistance (m $\Omega$ ) 30 25 20 15 10 5 6 7 8 9 10 4 VGS - Gate - Source Voltage (V)

**Gate Threshold Voltage** 

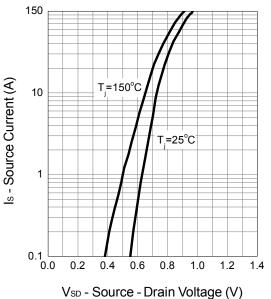




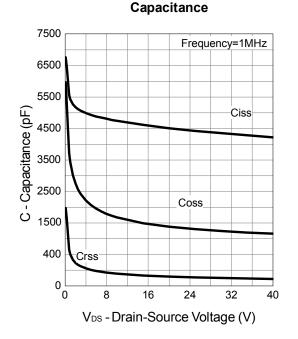
# **Typical Operating Characteristics (Cont.)**

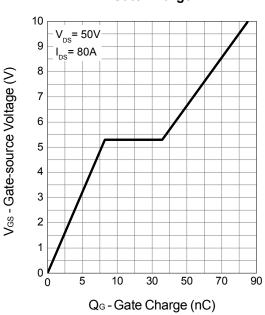


Drain-Source On Resistance Source-Drain Diode Forward



Gate Charge



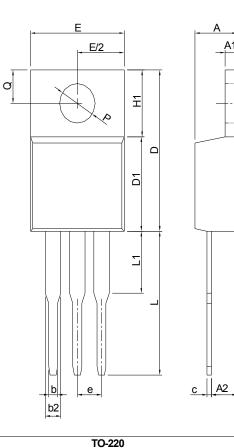




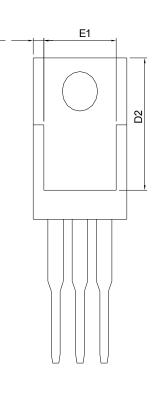
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### Package Information TO-220AB

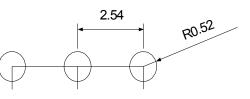


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### **RECOMMENDED LAND PATTERN**

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S ▼ MBO	MILLIME	ETERS	INC	HES	
ĮΫ	MIN.	MAX.	MIN.	MAX.	
Α	3.56	4.83	0.140	0.190	
A1	0.51	1.40	0.020	0.055	
A2	2.03	2.92	0.080	0.115	
b	0.38	1.02	0.015	0.040	
b2	1.14	1.78	0.045	0.070	
С	0.36	0.61	0.014	0.024	
D	14.22	16.51	0.560	0.650	
D1	8.38	9.02	0.330	0.355	
D2	12.19	13.65	0.480	0.537	
E	9.65	10.67	0.380	0.420	
E1	6.86	8.89	0.270	0.350	
е	2.54	BSC	0.10	D BSC	
H1	5.84	6.86	0.230	0.270	
L	12.70	14.73	0.500	0.580	
L1		6.35		0.250	
Р	3.53	4.09	0.139	0.161	
Q	2.54	3.43	0.100	0.135	



UNIT: mm



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